



Material Content Data Sheet



Sales Product Name		ESD113-B1-02EL E6327		Issued		7. February 2017		
MA#		MA001220736						
Package		PG-TSLP-2-20		Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.11		1142	
	noble metal	gold	7440-57-5	0.003	0.44		4433	
	inorganic material	silicon	7440-21-3	0.020	3.28	3.83	32849	38424
leadframe	non noble metal	nickel	7440-02-0	0.241	39.43	39.43	394274	394274
wire	noble metal	gold	7440-57-5	0.006	0.91	0.91	9139	9139
encapsulation	organic material	carbon black	1333-86-4	0.002	0.26		2621	
	plastics	epoxy resin	-	0.046	7.60		75982	
	inorganic material	silicondioxide	60676-86-0	0.272	44.55	52.41	445414	524017
leadfinish	noble metal	gold	7440-57-5	0.010	1.71	1.71	17073	17073
plating	noble metal	gold	7440-57-5	0.010	1.71	1.71	17073	17073
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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